

**WHAT IS CLAIMED IS**

1. A miniaturized small memory card to be set in an electric device, comprising :

A substrate having an upper surface and a lower surface, the upper surface  
5 formed with a plurality of connected points, the lower surface formed with a frame to cause a cavity formed between the frame and the substrate, the cavity also formed with a plurality of connected points, which electrically connected to a plurality of golden fingers of the frame, and the golden fingers are used to electrically connect to the electric device;

10 At least one upper memory chip, which formed on the upper surface of the substrate, electrically connected to a plurality of connected points of the upper surface;

At least one lower memory chip, which formed in the cavity on the lower surface of the substrate, electrically connected to a plurality of connected points of  
15 the lower surface;

An upper glue layer being encapsulated the upper surface of the substrate to cover at least one upper memory chip; and

A lower glue layer being encapsulated the lower surface of the substrate to cover at least one lower memory chip.

20 2. The miniaturized small memory card according to claim 1, wherein the

upper memory chips are electrically connected to the connected points of the upper surface of the substrate via a plurality of wires.

3. The miniaturized small memory card according to claim 1, wherein the lower memory chip is electrically connected to the connected points of the upper 5 surface of the substrate via a plurality of wires.

4. The miniaturized small memory card according to claim 1, wherein the upper memory chip is electrically connected to the connected points on the upper surface of the substrate via golden ball by coating manner.

5. The miniaturized small memory card according to claim 1, wherein the 10 lower memory chip is electrically connected to the connected points of the lower surface of the substrate via golden ball by coating manner.